

NLX2G04

Dual Inverter

The NLX2G04 MiniGate™ is an advanced high-speed CMOS dual inverter in ultra-small footprint.

The NLX2G04 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 1.8 \text{ ns (Typ) @ } V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu\text{A (Max) at } T_A = 25^\circ\text{C}$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

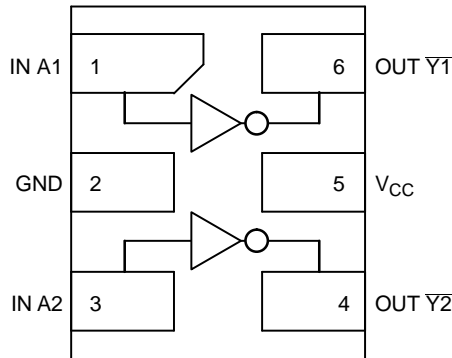


Figure 1. Pinout (Top View)

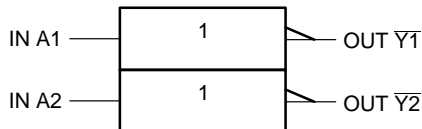


Figure 2. Logic Symbol

PIN ASSIGNMENT

| | |
|---|---------------------|
| 1 | IN A1 |
| 2 | GND |
| 3 | IN A2 |
| 4 | OUT $\overline{Y2}$ |
| 5 | V_{CC} |
| 6 | OUT $\overline{Y1}$ |

FUNCTION TABLE

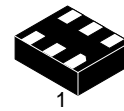
| A | \overline{Y} |
|---|----------------|
| L | H |
| H | L |



ON Semiconductor®

www.onsemi.com

MARKING DIAGRAMS



ULLGA6
1.2 x 1.0
CASE 613AE



UDFN6
1.0 x 1.0
CASE 517BX



UDFN6
1.2 x 1.0
CASE 517AA



UDFN6
1.45 x 1.0
CASE 517AQ



Q = Device Marking
M = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

NLX2G04

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|---------------|--|----------------------|-------------|
| V_{CC} | DC Supply Voltage | -0.5 to +7.0 | V |
| V_{IN} | DC Input Voltage | -0.5 to +7.0 | V |
| V_{OUT} | DC Output Voltage | -0.5 to +7.0 | V |
| I_{IK} | DC Input Diode Current $V_{IN} < GND$ | -50 | mA |
| I_{OK} | DC Output Diode Current $V_{OUT} < GND$ | -50 | mA |
| I_O | DC Output Source/Sink Current | ± 50 | mA |
| I_{CC} | DC Supply Current Per Supply Pin | ± 100 | mA |
| I_{GND} | DC Ground Current per Ground Pin | ± 100 | mA |
| T_{STG} | Storage Temperature Range | -65 to +150 | $^{\circ}C$ |
| T_L | Lead Temperature, 1 mm from Case for 10 Seconds | 260 | $^{\circ}C$ |
| T_J | Junction Temperature Under Bias | 150 | $^{\circ}C$ |
| MSL | Moisture Sensitivity | Level 1 | |
| F_R | Flammability Rating Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in | |
| $I_{LATCHUP}$ | Latchup Performance Above V_{CC} and Below GND at 125 $^{\circ}C$ (Note 2) | ± 500 | mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|---------------------|--|-------------|---------------|-------------|
| V_{CC} | Positive DC Supply Voltage | 1.65 | 5.5 | V |
| V_{IN} | Digital Input Voltage | 0 | 5.5 | V |
| V_{OUT} | Output Voltage | 0 | 5.5 | V |
| T_A | Operating Free-Air Temperature | -55 | +125 | $^{\circ}C$ |
| $\Delta t/\Delta V$ | Input Transition Rise or Fall Rate $V_{CC} = 2.5 V \pm 0.2 V$ $V_{CC} = 3.3 V \pm 0.3 V$ $V_{CC} = 5.0 V \pm 0.5 V$ | 0 0 0 | 20 10 5 | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NLX2G04

DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Conditions | V _{CC} (V) | T _A = 25°C | | | T _A = +85°C | | T _A = -55°C to +125°C | | Unit |
|--------------------------|----------------------------------|---|------------------------|------------------------|-----------------|------------------------|------------------------|------------------------|----------------------------------|------------------------|------|
| | | | | Min | Typ | Max | Min | Max | Min | Max | |
| V _{IH} | Low-Level Input Voltage | | 1.65–1.95 | 0.75 x V _{CC} | | | 0.75 x V _{CC} | | 0.75 x V _{CC} | | V |
| | | | 2.3 to 5.5 | 0.70 x V _{CC} | | | 0.70 x V _{CC} | | 0.70 x V _{CC} | | |
| V _{IL} | Low-Level Input Voltage | | 1.65–1.95 | | | 0.25 x V _{CC} | | 0.25 x V _{CC} | | 0.25 x V _{CC} | V |
| | | | 2.3 – 5.5 | | | 0.30 x V _{CC} | | 0.30 x V _{CC} | | 0.30 x V _{CC} | |
| V _{OH} | High-Level Output Voltage | V _{IN} = V _{IH} or V _{IL} I _{OH} = -100 μA | 1.65 – 5.5 | V _{CC} -0.1 | V _{CC} | | V _{CC} -0.1 | | V _{CC} -0.1 | | V |
| | | V _{IN} = V _{IH} or V _{IL} I _{OH} = -4 mA | 1.65 | 1.29 | 1.52 | | 1.29 | | 1.29 | | |
| | | I _{OH} = -8 mA | 2.3 | 1.9 | 2.1 | | 1.9 | | 1.9 | | |
| | | I _{OH} = -12 mA | 2.7 | 2.2 | 2.4 | | 2.2 | | 2.2 | | |
| | | I _{OH} = -16 mA | 3.0 | 2.4 | 2.7 | | 2.4 | | 2.4 | | |
| | | I _{OH} = -24 mA | 3.0 | 2.3 | 2.5 | | 2.3 | | 2.3 | | |
| I _{OH} = -32 mA | 4.5 | 3.8 | 4.0 | | 3.8 | | 3.8 | | | | |
| V _{OL} | Low-Level Output Voltage | V _{IN} = V _{IH} or V _{IL} I _{OL} = 100 μA | 1.65 – 5.5 | | | 0.1 | | 0.1 | | 0.1 | V |
| | | V _{IN} = V _{IH} or V _{IL} I _{OH} = -4 mA | 1.65 | | 0.08 | 0.24 | | 0.24 | | 0.24 | |
| | | I _{OH} = -8 mA | 2.3 | | 0.2 | 0.3 | | 0.3 | | 0.3 | |
| | | I _{OH} = -12 mA | 2.7 | | 0.22 | 0.4 | | 0.4 | | 0.4 | |
| | | I _{OH} = -16 mA | 3.0 | | 0.28 | 0.4 | | 0.4 | | 0.4 | |
| | | I _{OH} = -24 mA | 3.0 | | 0.38 | 0.55 | | 0.55 | | 0.55 | |
| I _{OH} = -32 mA | 4.5 | | 0.42 | 0.55 | | 0.55 | | 0.55 | | | |
| I _{IN} | Input Leakage Current | 0 ≤ V _{IN} ≤ 5.5 V | 0 to 5.5 | | | ±0.1 | | ±1.0 | | ±1.0 | μA |
| I _{OFF} | Power-Off Output Leakage Current | V _{IN} or V _{OUT} = 5.5 V | 0 | | | 1.0 | | 10 | | 10 | μA |
| I _{CC} | Quiescent Supply Current | 0 ≤ V _{IN} ≤ V _{CC} | 5.5 | | | 1.0 | | 10 | | 10 | μA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NLX2G04

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0$ nS)

| Symbol | Parameter | V _{CC} (V) | Test Condition | T _A = 25°C | | | T _A = -55°C to +125°C | | Unit |
|---|--|------------------------|--|---|-----|-----|-------------------------------------|-----|------|
| | | | | Min | Typ | Max | Min | Max | |
| t _{PLH} , t _{PHL} | Propagation Delay, Input A to Output Y | 1.65 | R _L = 1 MΩ, C _L = 15 pF | 1.8 | 2.3 | 9.2 | 1.8 | 11 | ns |
| | | 1.8 | R _L = 1 MΩ, C _L = 15 pF | 1.8 | 4.4 | 7.6 | 1.2 | 8.4 | |
| | | 2.3–2.7 | R _L = 1 MΩ, C _L = 15 pF | 1.2 | 3.0 | 5.1 | 1.2 | 5.6 | |
| | | 3.0–3.6 | R _L = 1 MΩ, C _L = 15 pF | 0.8 | 2.2 | 3.4 | 0.8 | 3.8 | |
| | | | | R _L = 500 Ω, C _L = 50 pF | 1.2 | 2.9 | 4.5 | 1.2 | |
| | | 4.5–5.5 | R _L = 1 MΩ, C _L = 15 pF | 0.5 | 1.8 | 2.8 | 0.5 | 3.1 | |
| R _L = 500 Ω, C _L = 50 pF | 0.8 | | | 2.3 | 3.6 | 0.8 | 4.0 | | |
| C _{IN} | Input Capacitance | 5.5 | V _{IN} = 0 V or V _{CC} | | 2.5 | | | | pF |
| C _{PD} | Power Dissipation Capacitance (Note 3) | 3.3 | 10 MHz | | 9 | | | | pF |
| | | 5.5 | V _{IN} = 0 V or V _{CC} | | 11 | | | | |

3. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

NLX2G04

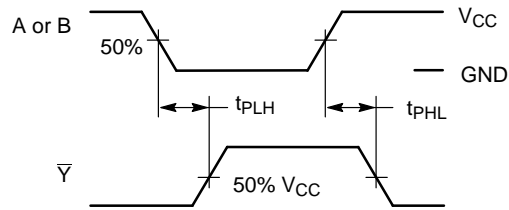


Figure 3. Switching Waveforms

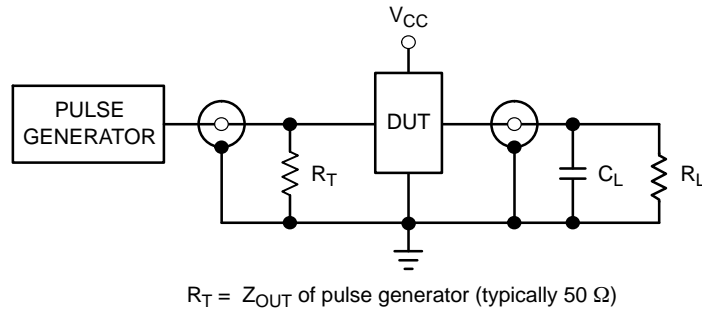


Figure 4. Test Circuit

ORDERING INFORMATION

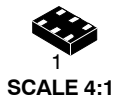
| Device | Package | Shipping† |
|----------------|--------------------------------------|--------------------|
| NLX2G04BMX1TCG | ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free) | 3000 / Tape & Reel |
| NLX2G04MUTCG | UDFN6, 1.2 x 1.0, 0.4P (Pb-Free) | 3000 / Tape & Reel |
| NLX2G04AMUTCG | UDFN6, 1.45 x 1.0, 0.5P (Pb-Free) | 3000 / Tape & Reel |
| NLX2G04CMUTCG | UDFN6, 1.0 x 1.0, 0.35P (Pb-Free) | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE

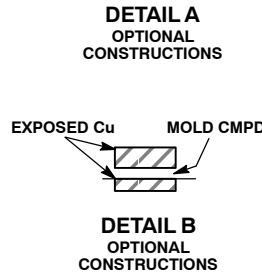
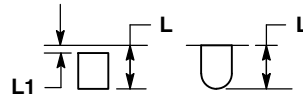
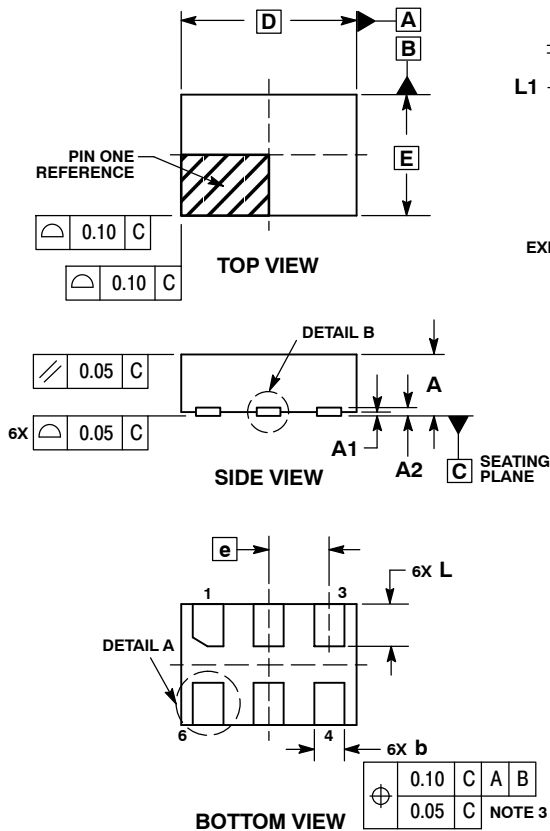
PACKAGE DIMENSIONS

ON Semiconductor®



UDFN6, 1.45x1.0, 0.5P
CASE 517AQ-01
ISSUE O

DATE 15 MAY 2008



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

| MILLIMETERS | | |
|-------------|------|------|
| DIM | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A2 | 0.07 | REF |
| b | 0.20 | 0.30 |
| D | 1.45 | BSC |
| E | 1.00 | BSC |
| e | 0.50 | BSC |
| L | 0.30 | 0.40 |
| L1 | --- | 0.15 |

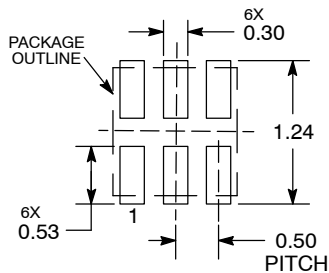
GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|---------------------------|--|
| DOCUMENT NUMBER: | 98AON30313E | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | UDFN6, 1.45X1.0, 0.5P | PAGE 1 OF 2 |

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

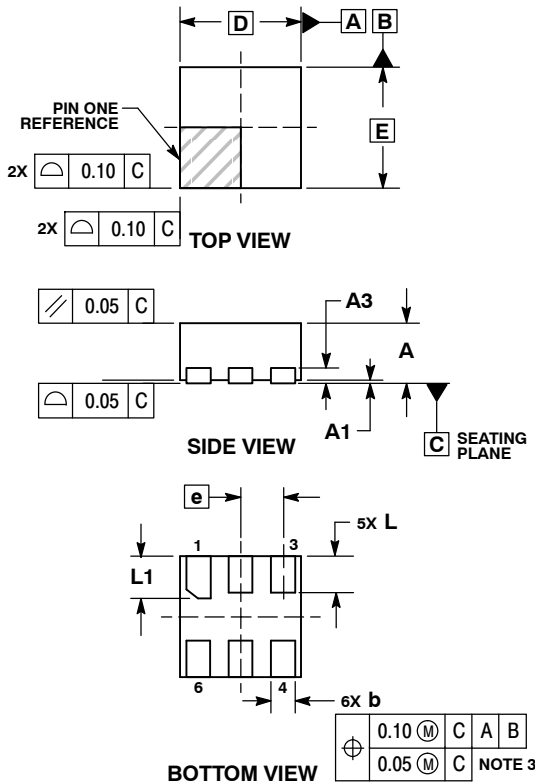
ON Semiconductor®



SCALE 4:1

UDFN6, 1x1, 0.35P
CASE 517BX-01
ISSUE O

DATE 18 MAY 2011

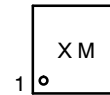


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

| MILLIMETERS | | |
|-------------|------|------|
| DIM | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A3 | 0.13 | REF |
| b | 0.12 | 0.22 |
| D | 1.00 | BSC |
| E | 1.00 | BSC |
| e | 0.35 | BSC |
| L | 0.25 | 0.35 |
| L1 | 0.30 | 0.40 |

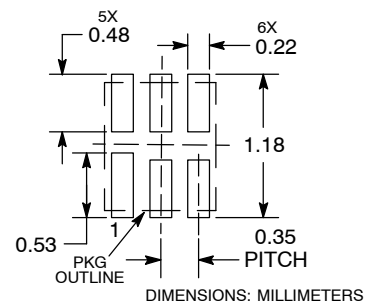
GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|---------------------------|--|
| DOCUMENT NUMBER: | 98AON56787E | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | UDFN6, 1X1, 0.35P | PAGE 1 OF 2 |

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

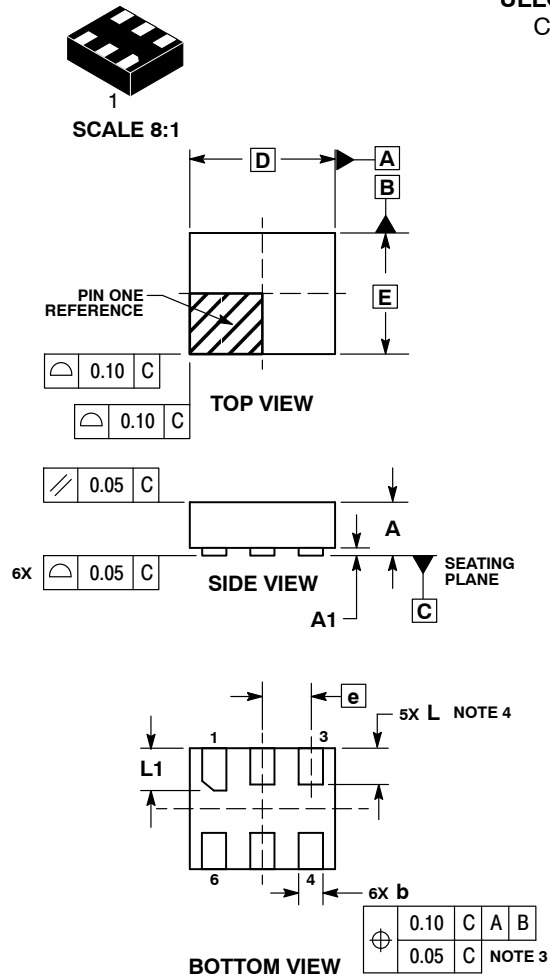


ULLGA6, 1.2x1.0, 0.4P

CASE 613AE-01

ISSUE A

DATE 06 FEB 2008



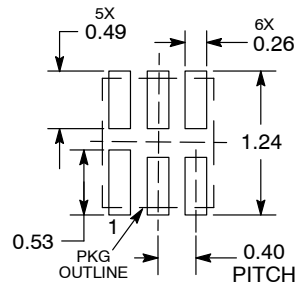
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

| MILLIMETERS | | |
|-------------|----------|------|
| DIM | MIN | MAX |
| A | --- | 0.40 |
| A1 | 0.00 | 0.05 |
| b | 0.15 | 0.25 |
| D | 1.20 BSC | |
| E | 1.00 BSC | |
| e | 0.40 BSC | |
| L | 0.25 | 0.35 |
| L1 | 0.35 | 0.45 |

MOUNTING FOOTPRINT

SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|------------------------------|--|
| DOCUMENT NUMBER: | 98AON24012D | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION: | ULLGA6, 1.2X1.0, 0.4P | PAGE 1 OF 1 |

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative